Date: 4/7/2021
Material Number: EFR32FG1P132F64GM48-C0
Pkg Config.: PK1133

Detailed Device Composition

No.	Homogeneous Material	Material Weight (mg)	Material Content	CAS Number	Material Weight (%)	Material Weight (mg)	ppm of Material	Wt % of Total Unit	ppm of Total Unit
1	Bond Wire	0.35	Copper	7440-50-8	96.000	0.332	960000	0.2408	2408
			Gold	7440-57-5	1.000	0.003	10000	0.0025	25
			Palladium	7440-05-3	3.000	0.010	30000	0.0075	75
2	Mold Compound	58.94	Carbon Black	1333-86-4	0.300	0.177	3000	0.1282	1282
			Epoxy Resin A	Proprietary	3.000	1.768	30000	1.2821	12821
			Epoxy Resin B	126-80-7	3.000	1.768	30000	1.2821	12821
			Metal Hydroxide	Proprietary	1.500	0.884	15000	0.6410	6410
			Phenol Resin (Proprietary)	Proprietary	5.000	2.947	50000	2.1368	21368
			Silica	7631-86-9	87.200	51.396	872000	37.2662	372662
3	Plating - External	2.62	Tin	7440-31-5	100.000	2.622	1000000	1.9012	19012
4	Leadframe	67.76	Copper	7440-50-8	97.500	66.066	975000	47.9034	479034
			Iron	7439-89-6	2.350	1.592	23500	1.1546	11546
			Phosphorous	7723-14-0	0.120	0.081	1200	0.0590	590
			Zinc	7440-66-6	0.030	0.020	300	0.0147	147
5	Plating - Internal	4.56	Silver	7440-22-4	100.000	4.560	1000000	3.3064	33064
6	Die Attach Epoxy	1.00	Acrylates	Proprietary	4.000	0.040	40000	0.0289	289
			Acrylic Resin	Proprietary	9.000	0.090	90000	0.0650	650
			Additive	Proprietary	1.500	0.015	15000	0.0108	108
			Butadiene Coploymer	Proprietary	1.000	0.010	10000	0.0072	72
			Epoxy Resin (Proprietary)	Proprietary	2.000	0.020	20000	0.0144	144
			Peroxide	Proprietary	0.500	0.005	5000	0.0036	36
			Polybutadiene Derivative	Proprietary	5.000	0.050	50000	0.0361	361
			Silver	7440-22-4	77.000	0.767	770000	0.5561	5561
7	Die	2.69	Silicon	7440-21-3	99.800	2.686	998000	1.9473	19473
			Silicon Dioxide	60676-86-0	0.200	0.005	2000	0.0039	39
	Total Unit Weight =	137.92				137.92		100.0000	1000000